# LNJ0F1C5FRA1

## Hight Bright Surface Mounting Chip LED

Strobe Type

## ■ Absolute Maximum Ratings $T_a = 25\pm3$ °C

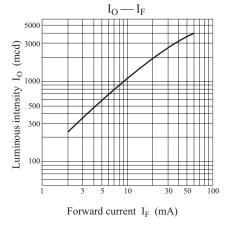
Parameter	Symbol	Rating	Unit	
Power dissipation	$P_{\mathrm{D}}$	103	mW	
Forward current	$I_{\mathrm{F}}$	25	mA	
Pulse forward current	$I_{FP}$	60	mA	
Reverse direct current	$I_{RDC}$	100	mA	
Operating ambient temperature	T <sub>opr</sub>	-30 to +85	°C	
Storage temperature	T <sub>stg</sub>	-40 to +100	°C	

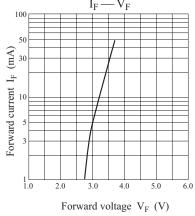
#### ■ Lighting Color

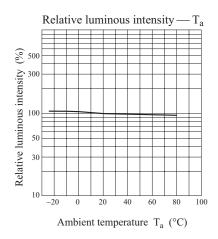
• White

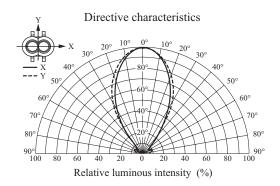
#### ■ Electro-Optical Characteristics $T_a = 25$ °C

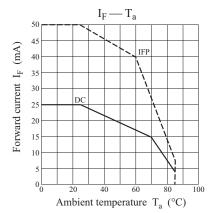
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity	I <sub>O-20</sub>	$I_F = 20 \text{ mA/chip DC}$	1500	2000		mcd
Forward voltage	$V_{\mathrm{F}}$	$I_F = 20 \text{ mA/chip DC}$	3.0	3.4	4.0	V
Chromaticity coordinates	X	I <sub>F</sub> = 20 mA/chip DC	0.280		0.340	_
	у	I <sub>F</sub> = 20 mA/chip DC	0.260		0.410	_





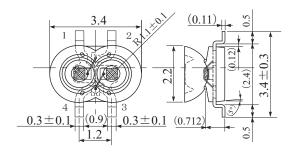


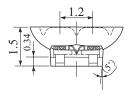


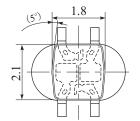


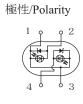
■ Package (Unit: mm)

## LLTLTN4GF100









- Pin name
  - 1, 3: Anode
  - 2, 4: Cathode

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